ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg	Informati	on		
upplier Inform									,					
Company name*			Company unique ID			Ţ	Unique ID Authority				Response Date*			
onsemi											2023-06-08			
Contact Name		Tit	Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewa	rds	Pro	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com			
uthorized Represei	ntative*	Tit	Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewa	rds	Pro	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester	Requester Item Number Mfr I		Item Number Mfr Item Name				Effective Date	Versio	n l	Manufacturing Site	We	ight*	UOM	Unit Type
		AMIS41683C	AMIS41683CANN1R LS FT CAN Transc. (3.3		sc. (3.3V)		2023-06-08		I	PHG		5.5	mg	Each
Ianufacturing l	Proccess Information	n						·						
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature Max Time at Pea		Temperature	Numb	er of Reflow Cyc	eles			
Matte Tin (Sn) - annealed		CU A	CU Alloy 2		2		260		С	30	seconds	3		
omments														
TTENTION: MSL	2 Rated item requires Di	ry Pack (after	electrical	test)		<u> </u>			·					
or more informatio	on regarding material con	nposition pleas	se refer to	page 3						·			·	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	7.01	mg	Supplier	Silicon (Si)	7440-21-3		7.01	mg
Die Attach	3.06	mg		Epoxy resin	proprietary data		0.0765	mg
			Supplier	Silver (Ag)	7440-22-4		2.5857	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0765	mg
			Supplier	Inorganic filler	Proprietary Data		0.0765	mg
			Supplier	Dicyandiamine	461-58-5		0.0153	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.2295	mg
Lead Frame	50.98	mg	Supplier	Zinc (Zn)	7440-66-6		0.0663	mg
			Supplier	Iron (Fe)	7439-89-6		1.198	mg
			Supplier	Copper (Cu)	7440-50-8		49.7004	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0153	mg
Mold Compound-Black	82.3	mg		Epoxy resin	proprietary data		4.115	mg
			Supplier	Phenolic Resin	Proprietary Data		1.646	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.0575	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4115	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		74.07	mg
Plating	1.67	mg	Supplier	Tin (Sn)	7440-31-5		1.67	mg
Wire Bond - Au	0.48	mg	Supplier	Gold (Au)	7440-57-5		0.48	mg